



Material Content Data Sheet



Sales Product Name		BSO211P H		Issued		24. January 2018		
MA#		MA000734806						
Package		PG-DSO-8-40		Weight*		82.39 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.109	1.35	1.35	13462	13462
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		119	
	non noble metal	zinc	7440-66-6	0.039	0.05		477	
	non noble metal	iron	7439-89-6	0.785	0.95		9530	
	non noble metal	copper	7440-50-8	31.880	38.70	39.71	386965	397091
wire	non noble metal	copper	7440-50-8	0.158	0.19	0.19	1923	1923
encapsulation	organic material	carbon black	1333-86-4	0.235	0.28		2850	
	plastics	epoxy resin	-	7.280	8.84		88363	
	inorganic material	silicondioxide	60676-86-0	39.452	47.88	57.00	478871	570084
leadfinish	non noble metal	tin	7440-31-5	0.814	0.99	0.99	9878	9878
plating	noble metal	silver	7440-22-4	0.063	0.08	0.08	763	763
glue	plastics	epoxy resin	-	0.084	0.10		1020	
	noble metal	silver	7440-22-4	0.476	0.58	0.68	5779	6799
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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